Call for Papers

SOLID MODELING 2002

Seventh ACM Symposium on Solid Modeling and Applications

Max−Planck−Institut für Informatik, Saarbrücken,Germany

June 17−21, 2002

Sponsored by ACM SIGGRAPH and EUROGRAPHICS

The Solid Modeling symposia series is an international forum for the exchange of recent research and applications of solid modelling, shape modelling, and geometric computation in design, analysis and manufacturing, as well as in the emerging biomedical, geophysical and other areas. This highly successful symposium, which has been held bi−annually since 1991, brings together prominent researchers, key practitioners, and numerous students in the field. Starting in 2002, it will be held annually, alternating in location between the USA and the other countries with a two year period. The Solid Modeling 2002 symposium will be held at the Max−Planck−Institut für Infomatik, in Saarbrücken, Germany. In addition to technical papers in plenary sessions, the program for Solid Modeling 2002 will include: − academic and industrial tutorials − keynote lectures − panel sessions − best paper award at the symposium banquet − sponsorship of students to attend the symposium − social program More information on the symposium can be found on the Solid Modeling 2002 web page:

http://www.mpi−sb.mpg.de/conferences/sm02/index.html

The papers submission schedule is as follows:

October 31, 2001:	Abstracts due
November 30, 2001:	Full papers due
February 28, 2002:	Notice of acceptance and reviews
March 31, 2002:	Final camera−ready papers and extended abstracts due

For details on how to submit abstracts and papers, please consult the web page. Abstracts are used to facilitate the review process and should be 150−300 words in length. Papers are limited to 12 typeset pages in length, including figures and references, and should present previously unpublished original results. All papers will be peer−reviewed and can be selected for presentation at a plenary session, or for presentation at a poster session, with publication in the conference proceedings published by ACM Press. A revised version of selected papers will be also published in special issues of Computer Aided Design journal and of the ASME/ACM journal Computer and Information Science in Engineering (JCISE). Best paper award will be selected by a jury of experts and will be presented at the symposium banquet.

Symposium Co–Chairs:

Hans–Peter Seidel, Max Planck Institute, Saarbruecken, Germany
Vadim Shapiro, University of Wisconsin, Madison, U.S.A.

Program Co–Chairs:

Kunwoo Lee, Seoul National University, Seoul, Korea
Nicholas M. Patrikalakis, MIT, Cambridge, U.S.A.

Topics of interest for Solid Modeling 2002 include, but are not limited to:

Geometric and topological representations
Multi–resolution models
Heterogeneous models
Geometric interrogations and reasoning
Computational geometry
Robustness of geometric computations
Blends, sweeps, offsets & deformations
Procedural, constraint–based and parametric modeling
Feature–based modeling
Conceptual design techniques
Product and assembly modeling
Representation conversion
Product data exchange
User interaction techniques
Haptic interfaces
Collaborative/distributed design
Virtual environments and prototypes
Reverse engineering
Engineering analysis using solid models
Engineering tolerances
Manufacturing and assembly planning
Computational support for new manufacturing technologies
Biomedical applications
Geoscience
Entertainment applications